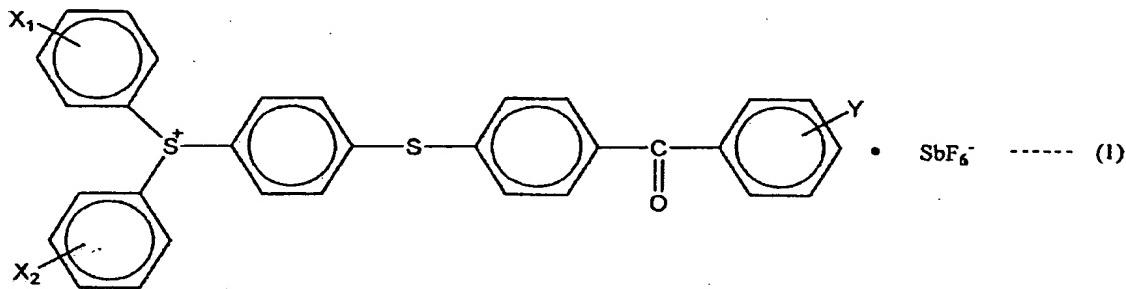


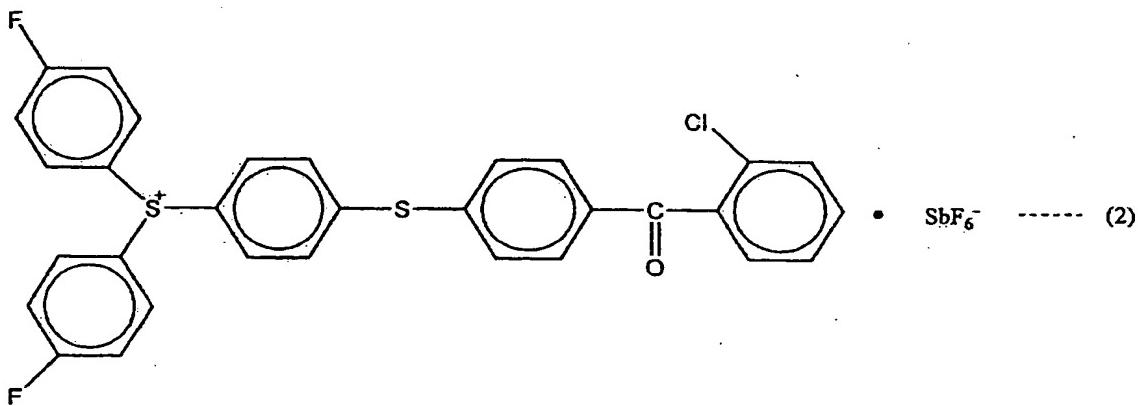
## CLAIMS

1. A photosensitive resin composition comprising:
    - a multi-functional epoxy resin; and
    - a cation polymerization initiator represented by general formula (1) shown below:



(in the formula,  $X_1$  and  $X_2$  indicate a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond, respectively, and they may be identical to or different from one another, and  $Y$  indicates a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond).

2. The photosensitive resin composition according to claim 1, wherein the multi-functional epoxy resin is a multi-functional bisphenol A novolak epoxy resin, and the cation polymerization initiator is a compound represented by chemical formula (2) shown below:



3. The photosensitive resin composition according to claim 1, further comprising a linear polymeric 2-functional epoxy resin.
4. The photosensitive resin composition according to claim 1, further comprising a naphthol sensitizer.
5. The photosensitive resin composition according to claim 1, further comprising  $\gamma$ -butyrolactone.
6. A photosensitive resin composition laminate comprising:  
a photosensitive resin composition layer obtained from the photosensitive resin composition according to claim 1; and  
a protective film,  
wherein at least one side of the photosensitive resin composition layer is protected with the protective film.
7. A method of forming a pattern comprising the steps of:  
applying the photosensitive resin composition according to claim 1 on a desired base and then drying the photosensitive resin composition;  
exposing a radiation beam on a photosensitive resin composition layer to form given resin patterns;  
developing the beam-exposed photosensitive resin composition layer; and

heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.

8. A method of forming a pattern comprising the steps of:
  - peeling the protective film away from the photosensitive resin composition laminate according to claim 6;
  - attaching a resulting photosensitive resin composition layer on a desired base;
  - exposing a radiation beam on the photosensitive resin composition layer to form a given pattern;
  - developing the beam-exposed photosensitive resin composition layer; and
  - heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.